

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

BVxxC-MS

Product specification

DESCRIPTION

The BVxxC-MS Series are ultra low capacitance transient voltage suppressor arrays, designed to protect applications such as portable electronics and SMART phones. This series is available in bidirectional configurations and is rated at 300 Watts for an 8/20 μ s wave shape.

The BVxxC-MS Series meets IEC 61000-4-2 (ESD) and IEC 61000-4-4 (EFT) requirements. At higher operating frequencies or faster edge rates, insertion loss and signal integrity are a major concern. This series offers ultra low capacitance and low leakage current in a miniature SOD-323 package.

FEATURES

- IEC61000-4-2 (ESD) \pm 30kV (Contact)
IEC61000-4-2 (ESD) \pm 30kV (Air)
IEC61000-4-4 (EFT) 40A (5/50ns)
- Protects one I/O line (bidirectional)
- Low clamping voltage
- Working voltages: 3V, 5V, 8V, 12V, 15V, 24V
- Low leakage current
- Response Time is < 1 ns


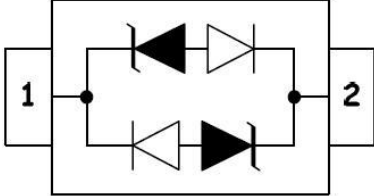
MACHANICAL DATA

- SOD-323 package
- Flammability Rating: UL 94V-0
- Packaging: Tape and Reel
- High temperature soldering guaranteed:260 $^{\circ}$ C/10s
- Reel size: 7 inch

APPLICATIONS

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Peripherals
- USB Interface

Reference News

SOD-323	PIN CONFIGURATION
	

MARKING

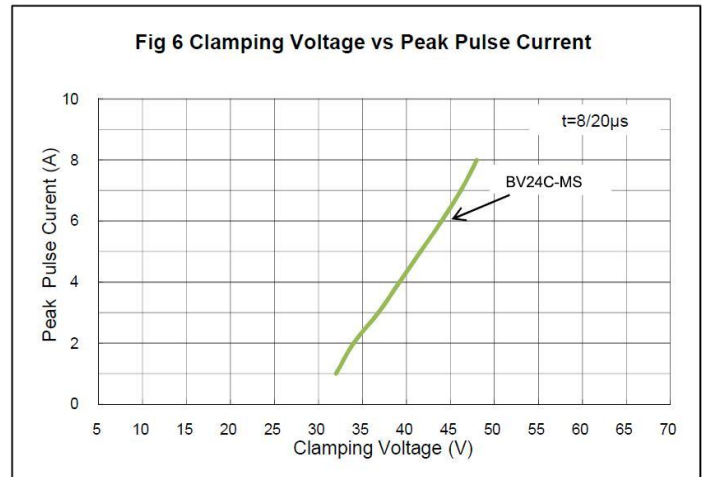
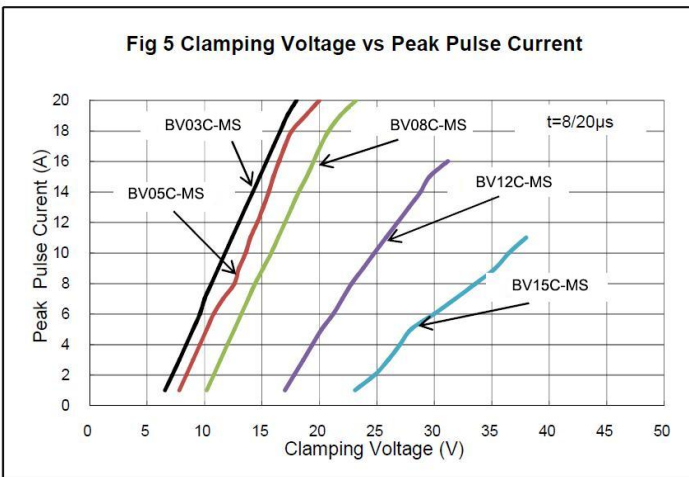
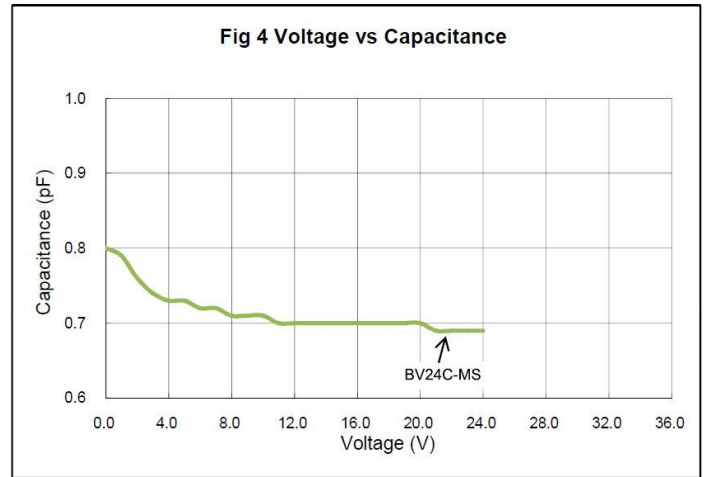
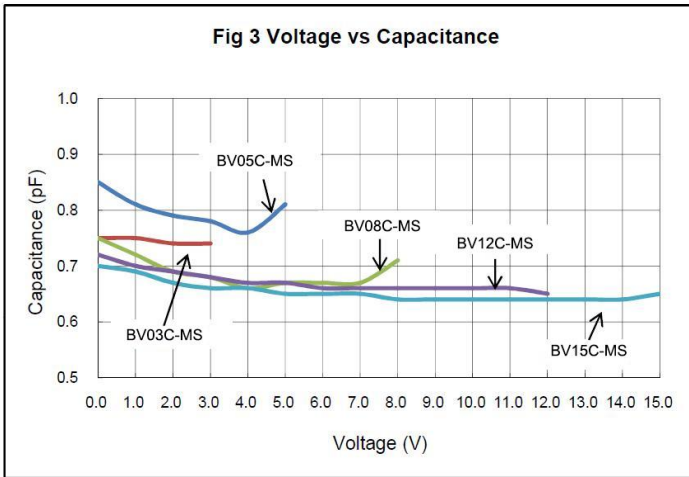
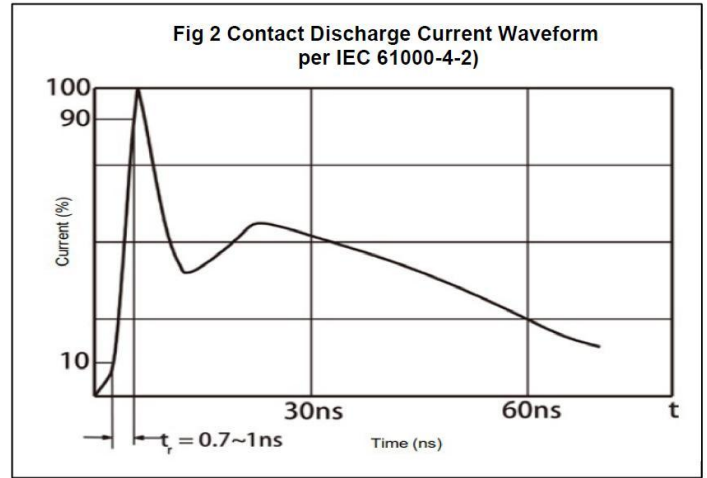
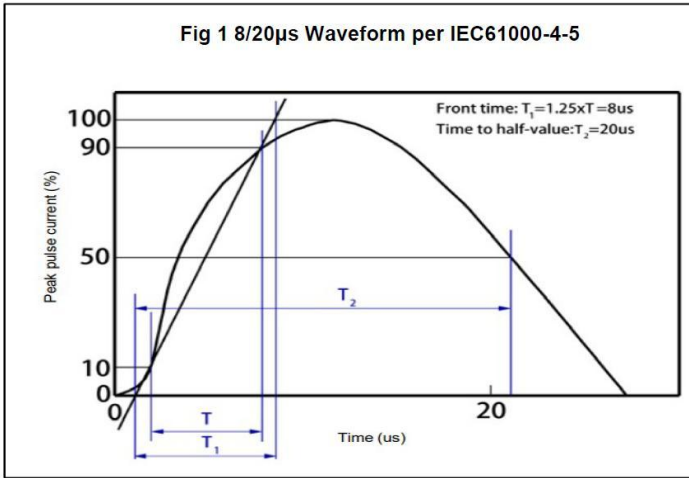
BV03C-MS	BV05C-MS	BV08C-MS	BV12C-MS	BV15C-MS	BV24C-MS
CC	AC	BC	DC	EC	HC

ABSOLUTE MAXIMUM RATING

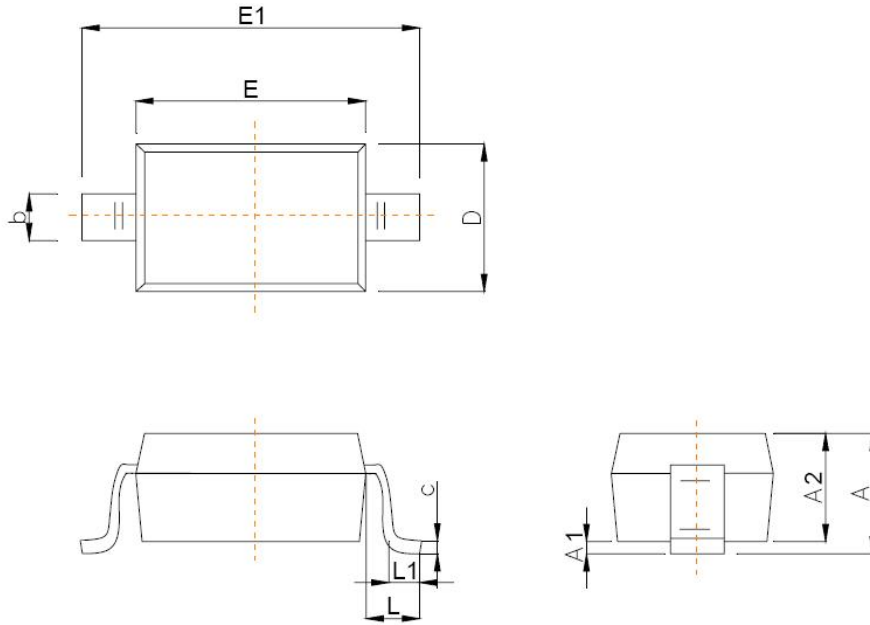
Symbol	Parameter	Value	Units
V _{ESD}	ESD per IEC 61000-4-2 (Contact) ESD per IEC 61000-4-2 (Air)	±30 ±30	kV
P _{PP}	Peak Pulse Power (8/20μs)	350	W
T _{OPT}	Operating Temperature	-55/+150	°C
T _{STG}	Storage Temperature	-55/+150	°C
T _L	Lead Soldering Temperature	260	°C

PART NUMBER	V _{RWM} (V) (max.)	V _B (V) (min.)	I _T (mA)	V _{C@1A} (V) (max.)	V _C (V)		I _R (μA) (max.)	C _T (pF) (typ.)
					(max.)	(@A)		
BV03C-MS	3.0	4.0	1	7.0	20	20	5	0.8
BV05C-MS	5.0	6.0	1	9.8	20	18	1	0.8
BV08C-MS	8.0	8.5	1	13.4	24	18	1	0.8
BV12C-MS	12.0	13.3	1	19.0	28.6	12	1	0.8
BV15C-MS	15.0	16.7	1	24.0	31.8	10	1	0.8
BV24C-MS	24.0	26.7	1	43.0	56.0	6	1	0.8

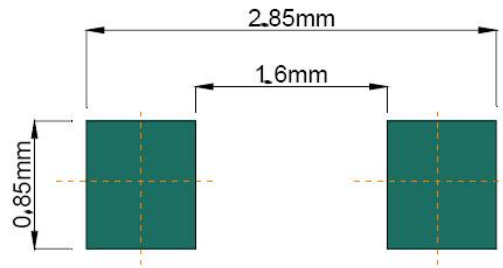
ELECTRICAL CHARACTERISTICS CURVE



SOD-323PACKAGEOUTLINEDIMENSIONS



Symbol	Dimensions In Millimeters	
	Min	Max
A		1.00
A1	0.000	0.100
A2	0.800	0.900
b	0.250	0.350
c	0.080	0.150
D	1.200	1.400
E	1.600	1.800
E1	2.500	2.700
e	1.800	2.040
L	0.475 REF	
L1	0.250	0.400
θ	0°	8°



Recommended Pad outline

REELSPECIFICATION

P/N	PKG	QTY
BVxxC-MS	SOD-323	3000

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